BGB741L7ESD

ESD-Robust and Easy-To-Use Broadband LNA MMIC

RF & Protection Devices



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BGB741L7ESD, ESD-Robust and Easy-To-Use Broadband LNA MMIC

Revision History: 2009-04-17, Rev. 1.0

Prevision History: no previous version

Page	Subjects (major changes since last revision)



ESD-Robust and Easy-To-Use Broadband LNA MMIC

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ESD-Robust and Easy-To-Use Broadband LNA MMIC

Features

- High-performance broadband LNA MMIC for applications between 50 MHz and 5.5 GHz
- Integrated stabilization, biasing, matching and ESD-protection simplifies design and reduces external parts count
- Integrated active biasing circuit makes operation point highly stable against temperature- and processing-variations
- Integrated ESD protection: RF input pin typical 4 kV vs. GND, RF output pin 2.5 kV vs. GND (HBM stress pulses)
- Supply voltage 1.8 4.0 V
- Adjustable current 6 mA to 30 mA by an external resistor
- Power-off function
- Excellent noise figure for a broadband LNA by using latest SiGe:C bipolar technolgy
- High linearity due to active biasing
- Very small, leadless, Pb-free (RoHS compliant) and halogen-free (WEEE compliant) "green" package TSLP-7-1, 2.0 x 1.3 x 0.4 mm



Applications

• Mobile TV, DAB, RKE, AMR, Cellular, ZigBee, WiMAX, SDARs, WiFi, Cordless phone, UMTS, WLAN, UWB

2 Product Brief

The BGB741L7ESD is an advanced high performance low noise amplifier (LNA) MMIC which simplifies the design of arbitrary LNA application circuits. Due to its integrated feedback the device is perfectly matched up to 3.5 GHz. The integrated biasing further reduces external parts count and stabilizes the bias current against temperatureand process-variations. The integrated feedback provides unconditional stability and eases the design process. The device is highly flexible because the bias current is adjustable and the device works with a broad supply voltage range. The BGB741L7ESD is based upon Infineon Techologies' cost effective bipolar silicon germanium carbon (SiGe:C) technology and comes in a low profile TSLP-7-1 leadless "green" package.

Туре	Package	Marking
BGB741L7ESD	TSLP-7-1	AY





BGB741L7ESD

Product Brief

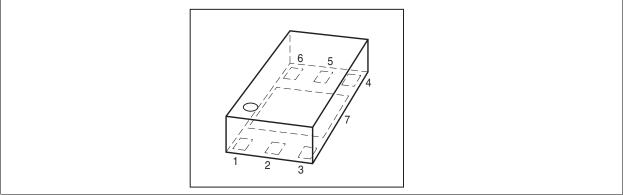


Figure 1 Pin configuration

Table 1 Pinning table

Pin	Function
1	V _{cc}
2	Bias-Out
3	RF-In
4	RF-Out
5	Control On/Off
6	Current Adjust
7	GND

The following diagram shows the principal schematic how the BGB741L7ESD is used in a circuit. The Power On/Off function is used by applying V_{ctrl} . By applying an external resistor R_{ext} the pre-set current of 6mA (which is adjusted by the integrated biasing when R_{ext} is omitted) can be increased. Base- and collector voltages are applied to the respective RFin- and RFout-pins by external inductors.

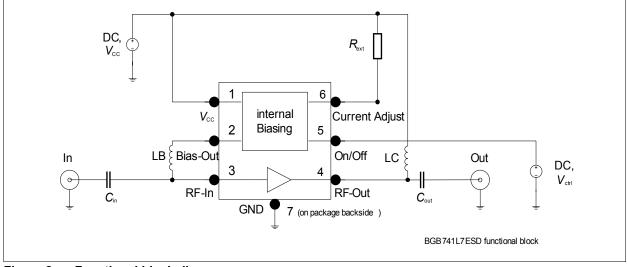


Figure 2 Functional block diagram



Maximum Ratings

3 Maximum Ratings

Parameter	Symbol	Value	Unit
Supply voltage	V _{CC}	4.0	V
$T_A = -55^{\circ}C$		3.5	
Supply current at V _{CC} pin	I _{CC}	30	mA
DC current at RF In pin	IB	3	mA
Voltage at Control On / Off pin	V _{ctrl}	4.0	V
Total power dissipation ¹⁾	P _{tot}	120	mW
T _s <117°C			
Operation junction temperature	T _{JOp}	-55150	°C
Storage temperature	T _{Stg}	-55150	°C

Table 2	Maximum ratings at $T = 25^{\circ}C$ (uplace atherwise aposition)
Table Z	Maximum ratings at $T_{A} = 25^{\circ}C$ (unless otherwise specified)

1) The soldering point temperature $T_{\rm S}$ measured at the GND pin (7) at the soldering point to the pcb

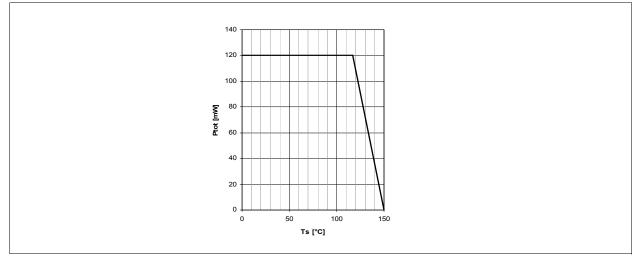
Note: Exceeding only one of the above maximum rating limits even for a short moment may cause permanent damage to the device. Even if the device continues to operate, its lifetime may be considerably shortened. Maximum ratings are stress ratings only and do not mean unaffected functional operation and lifetime at others than standard operation conditions.

4 Thermal Characteristics

Table 3 Thermal Resistance

Parameter	Symbol	Value	Unit	
Junction - soldering point ¹⁾	R _{thJS}	275	K/W	

1) For calculation of $R_{\rm thJA}$ please refer to Application Note Thermal Resistance







Operation Conditions

5 Operation Conditions

Table 4 Operation Conditions

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Supply voltage	V _{CC}	1.8	3.0	4.0	V	
Voltage Control On/Off pin in On mode	V _{ctrl-on}	1.2		4.0	V	
Voltage Control On/Off pin in Off mode	$V_{\rm ctrl-off}$	-0.3		0.3	V	

6 Electrical Characteristics

6.1 DC Characteristics

Parameter	Symbol	Values			Unit	Note /
		Min.	lin. Typ.	Max.		Test Condition
Supply current in On-mode	I _{CC}	5.0	6.0 10	7.2	mA	$R_{ext} = open$ $R_{ext} = 4 k\Omega$ $V_{CC} = 3.0 V$ $V_{ctrl} = 3.0 V$ (Small signal operation)
Supply current in Off mode	I _{CC-off}			6.0	μA	$V_{\rm CC}$ = 3.0 V $V_{\rm ctrl}$ = 0 V
Current into Control On/Off pin in On- mode	I _{ctrl-on}		14	20	μA	$V_{\rm CC}$ = 3.0 V $V_{\rm ctrl}$ = 3.0 V
Current into Control On/Off pin in Off- mode	I _{ctrl-off}			0.1	μA	$V_{\rm CC}$ = 3.0 V $V_{\rm ctrl}$ = 0 V

Table 5DC characteristics at T_A = 25 °C



6.2 AC Characteristics

The measurement setup is a test fixture with Bias-T's in a 50 Ω system, T_A = 25 °C.

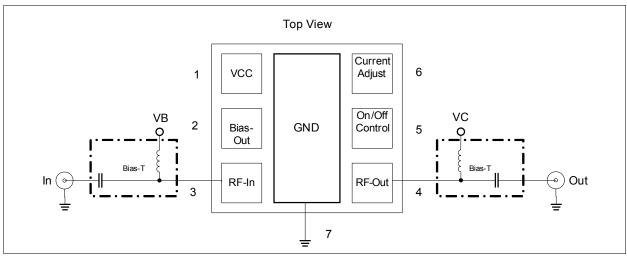


Figure 4 BGB741L7ESD testing setup

Table 6AC Characteristics, $V_c = 3 V$, f = 150 MHz

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Minimum Noise Figure ¹⁾	NF _{min}		1.05 0.95		dB	$Z_{\rm S} = Z_{\rm Sopt}$ $I_{\rm C} = 6 \text{ mA}$ $I_{\rm C} = 10 \text{ mA}$
Noise Figure in 50 Ω System ²⁾	NF 50		1.1 1.05		dB	$Z_{\rm S} = Z_{\rm L} = 50\Omega$ $I_{\rm C} = 6 \text{ mA}$ $I_{\rm C} = 10 \text{ mA}$
Transducer Gain	S ₂₁ ²		19 21		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Maximum Stable Power Gain	$G_{\sf ms}$		20 21.5		dB	$Z_{L} = Z_{Lopt}, Z_{S} = Z_{Sc}$ $I_{C} = 6 \text{ mA}$ $I_{C} = 10 \text{ mA}$
Input 1 dB Gain compression point ³⁾	IP _{1dB}		-5.5 -8		dBm	I_{Cq} = 6 mA I_{Cq} = 10 mA
Input 3 rd Order Intercept Point	IIP ₃		5.5 3.5		dBm	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Input Return Loss	<i>R.L.</i> _{in}		14 18		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Output Return Loss	R.L. _{out}		12.5 18.5		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{Cq} is the quiescent current, that is at small RF input power level. I_C increases as RF input power level approaches P1dB.



Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Minimum Noise Figure ¹⁾	NF _{min}				dB	$Z_{\rm S}$ = $Z_{\rm Sopt}$
-			1.05			$I_{\rm C} = 6 \mathrm{mA}$
			0.95			$I_{\rm C} = 10 {\rm mA}$
Noise Figure in 50 Ω System ²⁾	NF ₅₀				dB	$Z_{\rm S}$ = $Z_{\rm I}$ = 50 Ω
			1.1			$I_{\rm C} = 6 \mathrm{mA}$
			1.05			$I_{\rm C} = 10 {\rm mA}$
Transducer Gain	$ S_{21} ^2$		18.5		dB	$I_{\rm C}$ = 6 mA
			20.5			$I_{\rm C} = 10 {\rm mA}$
Maximum Available Power Gain	G_{ma}				dB	$Z_{\rm L} = Z_{\rm Lopt}, Z_{\rm S} = Z_{\rm Sopt}$
			19			$I_{\rm C}$ = 6 mA
			20.5			$I_{\rm C}$ = 10 mA
Input 1 dB Gain compression point ³⁾	IP _{1dB}		-5		dBm	$I_{Ca} = 6 \text{ mA}$
			-7.5			$I_{Cq} = 10 \text{ mA}$
Input 3 rd Order Intercept Point	IIP ₃		4		dBm	$I_{\rm C}$ = 6 mA
			2.5			$I_{\rm C} = 10 {\rm mA}$
Input Return Loss	$R.L{in}$		15.5		dB	$I_{\rm C}$ = 6 mA
			21			$I_{\rm C}$ = 10 mA
Output Return Loss	R.L. _{out}		14.5		dB	$I_{\rm C}$ = 6 mA
	0111		28			$I_{\rm C} = 10 {\rm mA}$

Table 7 AC Characteristics, $V_c = 3 V$, f = 450 MHz

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{Cq} is the quiescent current, that is at small RF input power level. I_C increases as RF input power level approaches P1dB.

Table 8AC Characteristics, $V_c = 3 V$, f = 900 MHz

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Minimum Noise Figure ¹⁾	NF _{min}		1.05 0.95		dB	$Z_{\rm S} = Z_{\rm Sopt}$ $I_{\rm C} = 6 \text{ mA}$ $I_{\rm C} = 10 \text{ mA}$
Noise Figure in 50 Ω System ²⁾	NF ₅₀		1.1 1.05		dB	$Z_{\rm S} = Z_{\rm L} = 50\Omega$ $I_{\rm C} = 6 \text{ mA}$ $I_{\rm C} = 10 \text{ mA}$
Transducer Gain	S ₂₁ ²		18.5 20		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Maximum Available Power Gain	G _{ma}		19 20.5		dB	$Z_{L} = Z_{Lopt}, Z_{S} = Z_{Sopt}$ $I_{C} = 6 \text{ mA}$ $I_{C} = 10 \text{ mA}$
Input 1 dB Gain compression point ³⁾	IP _{1dB}		-5 -7		dBm	$I_{Cq} = 6 \text{ mA}$ $I_{Cq} = 10 \text{ mA}$
Input 3 rd Order Intercept Point	IIP ₃		3 1.5		dBm	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA



Parameter	Symbol	Values			Unit	Note /
		Min. T	Тур.	Max.		Test Condition
Input Return Loss	<i>R.L.</i> _{in}		15.5 19		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Output Return Loss	R.L. _{out}		14.5 28.5		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA

Table 8AC Characteristics, $V_c = 3 V$, (cont'd)f = 900 MHz

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{cq} is the quiescent current, that is at small RF input power level. I_c increases as RF input power level approaches P1dB.

Parameter Note / Symbol Values Unit **Test Condition** Max. Min. Тур. Minimum Noise Figure¹⁾ $Z_{\rm S} = Z_{\rm Sopt}$ NF_{min} dB $I_{\rm C} = 6 \, {\rm mA}$ 1.05 1.0 $I_{\rm C} = 10 \, {\rm mA}$ $Z_{\rm S} = Z_{\rm L} = 50\Omega$ Noise Figure in 50 Ω System²⁾ NF_{50} dB *I*_C = 6 mA 1.1 1.05 *I*_C = 10 mA Transducer Gain $I_{\rm C}$ = 6 mA $|S_{21}|^2$ 18 dB $I_{\rm C} = 10 \, {\rm mA}$ 19.5 $G_{\rm ma}$ $Z_{\rm L} = Z_{\rm Lopt}, Z_{\rm S} = Z_{\rm Sopt}$ Maximum Available Power Gain dB $I_{\rm C} = 6 \, {\rm mA}$ 18.5 20 $I_{\rm C} = 10 \, {\rm mA}$ $I_{Cq} = 6 \text{ mA}$ Input 1 dB Gain compression point $I\!P_{1dB}$ -4.5 dBm $I_{Cq} = 10 \text{ mA}$ -6.5 Input 3rd Order Intercept Point³⁾ IIP₃ 2.5 dBm $I_{\rm C}$ = 6 mA *I*_C = 10 mA 1 Input Return Loss $R.L._{in}$ 14.5 dB $I_{\rm C}$ = 6 mA 16 $I_{\rm C} = 10 \, {\rm mA}$ **Output Return Loss** R.L. out 14 dB $I_{\rm C}$ = 6 mA 23 $I_{\rm C}$ = 10 mA

Table 9 AC Characteristics, $V_c = 3 V$, f = 1500 MHz

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{Cq} is the quiescent current, that is at small RF input power level. I_C increases as RF input power level approaches P1dB.



Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Minimum Noise Figure ¹⁾	NF _{min}		1.05 1.05		dB	$Z_{\rm S} = Z_{\rm Sopt}$ $I_{\rm C} = 6 \text{ mA}$ $I_{\rm C} = 10 \text{ mA}$
Noise Figure in 50 Ω System ²⁾	NF 50		1.15 1.1		dB	$Z_{\rm S} = Z_{\rm L} = 50\Omega$ $I_{\rm C} = 6 \text{ mA}$ $I_{\rm C} = 10 \text{ mA}$
Transducer Gain	$ S_{21} ^2$		17.5 19		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Maximum Available Power Gain	G _{ma}		18 19.5		dB	$Z_{L} = Z_{Lopt}, Z_{S} = Z_{Sopt}$ $I_{C} = 6 \text{ mA}$ $I_{C} = 10 \text{ mA}$
Input 1 dB Gain compression point	IP _{1dB}		-4 -6		dBm	$I_{Cq} = 6 \text{ mA}$ $I_{Cq} = 10 \text{ mA}$
Input 3 rd Order Intercept Point ³⁾	IIP ₃		2.5 1		dBm	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Input Return Loss	$R.L{in}$		13.5 15		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Output Return Loss	R.L. _{out}		13.5 21		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA

Table 10 AC Characteristics, $V_c = 3 V$, f = 1900 MHz

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{Cq} is the quiescent current, that is at small RF input power level. I_C increases as RF input power level approaches P1dB.

Table 11 AC Characteristics, $V_c = 3 V$, f = 2400 MHz

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Minimum Noise Figure ¹⁾	NF _{min}		1.1		dB	$Z_{\rm S} = Z_{\rm Sopt}$ $I_{\rm C} = 6 {\rm mA}$
2)	210		1.05			$I_{\rm C} = 10 {\rm mA}$
Noise Figure in 50Ω System ²⁾	NF 50		1.15 1.1		dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω $I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Transducer Gain	$ S_{21} ^2$		17 18.5		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Maximum Available Power Gain	G _{ma}		17.5 19		dB	$Z_{L} = Z_{Lopt}, Z_{S} = Z_{Sopt}$ $I_{C} = 6 \text{ mA}$ $I_{C} = 10 \text{ mA}$
Input 1 dB Gain compression point ³⁾	IP _{1dB}		-3.5 -5.5		dBm	$I_{Cq} = 6 \text{ mA}$ $I_{Cq} = 10 \text{ mA}$
Input 3 rd Order Intercept Point	IIP ₃		3 1		dBm	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA



Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Input Return Loss	<i>R.L.</i> _{in}		12.5 13.5		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA
Output Return Loss	R.L. _{out}		12.5 18		dB	$I_{\rm C}$ = 6 mA $I_{\rm C}$ = 10 mA

Table 11 AC Characteristics, $V_c = 3 V$, (cont'd)f = 2400 MHz

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{Cq} is the quiescent current, that is at small RF input power level. I_C increases as RF input power level approaches P1dB.

Table 12 AC Characteristics, $V_c = 3 V$, f = 3500 MHz

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Minimum Noise Figure ¹⁾	NF _{min}				dB	$Z_{\rm S} = Z_{\rm Sopt}$
-			1.25			$I_{\rm C} = 6 \mathrm{mA}$
			1.2			$I_{\rm C} = 10 {\rm mA}$
Noise Figure in 50 Ω System ²⁾	NF_{50}				dB	$Z_{\rm S} = Z_{\rm L} = 50\Omega$
	00		1.35			$I_{\rm C} = 6 \mathrm{mA}$
			1.25			$V_{\rm C}$ = 10 mA
Transducer Gain	$ S_{21} ^2$		15		dB	$I_{\rm C}$ = 6 mA
			16.5			$I_{\rm C}$ = 10 mA
Maximum Available Power Gain	G_{ma}				dB	$Z_{\rm L} = Z_{\rm Lopt}, Z_{\rm S} = Z_{\rm Sop}$
	ind		16			$I_{\rm C} = 6 \mathrm{mA}$
			17.5			$I_{\rm C}$ = 10 mA
Input 1 dB Gain compression point ³⁾	IP _{1dB}		-2.5		dBm	$I_{Cq} = 6 \text{ mA}$
	142		-4.5			$I_{Cq}^{q} = 10 \text{ mA}$
Input 3 rd Order Intercept Point	IIP ₃		3.5		dBm	$I_{\rm C}$ = 6 mA
			1.5			$I_{\rm C} = 10 {\rm mA}$
Input Return Loss	$R.L{in}$		10		dB	<i>I</i> _C = 6 mA
			10.5			$\tilde{I_{\rm C}}$ = 10 mA
Output Return Loss	R.L. _{out}		10		dB	<i>I</i> _C = 6 mA
	0111		13.5			$V_{\rm C}$ = 10 mA

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{Cq} is the quiescent current, that is at small RF input power level. I_C increases as RF input power level approaches P1dB.



Table 13	AC Characteristics,	$V_c = 3 V$,	<i>f</i> = 5500 MHz
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Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Minimum Noise Figure ¹⁾	NF _{min}				dB	$Z_{\rm S}$ = $Z_{\rm Sopt}$
-			1.8			$I_{\rm C} = 6 \mathrm{mA}$
			1.75			$I_{\rm C}$ = 10 mA
Noise Figure in 50 Ω System ²⁾	NF_{50}				dB	$Z_{\rm S} = Z_{\rm L} = 50\Omega$
			1.95			$I_{\rm C} = 6 \mathrm{mA}$
			1.85			$I_{\rm C}$ = 10 mA
Transducer Gain	$ S_{21} ^2$		12		dB	<i>I</i> _C = 6 mA
			13			$I_{\rm C}$ = 10 mA
Maximum Available Power Gain	$G_{\sf ma}$				dB	$Z_{\rm L} = Z_{\rm Lopt}, Z_{\rm S} = Z_{\rm Sopt}$
			14			$I_{\rm C}$ = 6 mA
			15			$I_{\rm C}$ = 10 mA
Input 1 dB Gain compression point ³⁾	IP _{1dB}		-1		dBm	$I_{Ca} = 6 \text{ mA}$
	142		-3			$I_{Cq} = 10 \text{ mA}$
Input 3 rd Order Intercept Point	IIP ₃		8.5		dBm	$I_{\rm C}$ = 6 mA
			4			$I_{\rm C} = 10 {\rm mA}$
Input Return Loss	$R.L{in}$		7		dB	<i>I</i> _C = 6 mA
			8			$I_{\rm C}$ = 10 mA
Output Return Loss	R.L. _{out}		7		dB	<i>I</i> _C = 6 mA
			8.5			$I_{\rm C}$ = 10 mA

1) Test fixture losses extracted

2) Test fixture losses extracted

3) Measured on an application board according to figure 2) presenting roughly a 50 Ω system to the device. I_{Cq} is the quiescent current, that is at small RF input power level. I_C increases as RF input power level approaches P1dB.



Package Information

7 Package Information

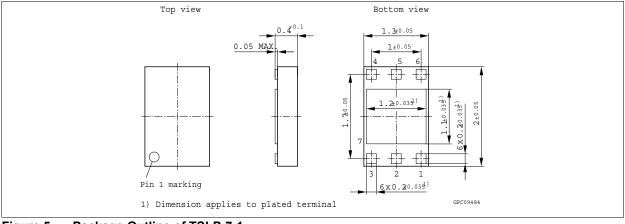


Figure 5 Package Outline of TSLP-7-1

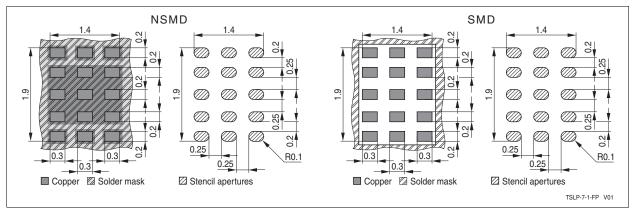
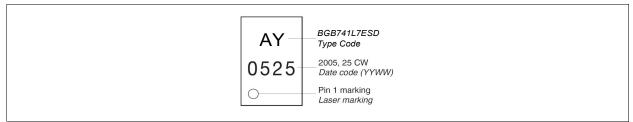
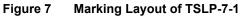


Figure 6 Foot Print of TSLP-7-1





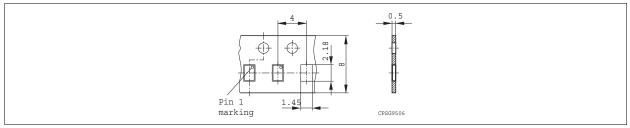


Figure 8 Tape of TSLP-7-1